

WHAT IS CLAIMED IS:

1. An integrated circuit package, comprising:
 - a) a pattern of contact pads applied to a surface of the integrated circuit package; and
 - b) a number of annular ring shaped alignment pads applied to said surface at known locations with respect to said pattern of contact pads.
- 5 2. An integrated circuit package as in claim 1, wherein said number of annular ring shaped alignment pads is three.
3. An integrated circuit package as in claim 1, further comprising a number of alignment members attached to said number of annular ring shaped alignment pads.
4. An integrated circuit package as in claim 3, wherein at least one of said number of alignment members is an alignment ball.
5. An integrated circuit package as in claim 3, wherein at least one of said number of alignment members is an alignment bullet having an end which is shaped to protrude into one of said number of annular ring shaped alignment pads.
6. An integrated circuit package as in claim 5, wherein said end of said at least one alignment bullet comprises a raised disc.
7. An integrated circuit package as in claim 3, wherein at least one of said number of alignment members is hard enough to resist deformation as said integrated circuit package is aligned with an interface.

8. An integrated circuit package as in claim 3, wherein diameters of said number of annular ring shaped alignment pads are smaller than diameters of said number of alignment members.
9. An integrated circuit package as in claim 1, further comprising a wetting media deposited to said number of annular ring shaped alignment pads.
10. An integrated circuit package as in claim 9, further comprising a number of alignment members attached to said number of annular ring shaped alignment pads via said wetting media.
11. An integrated circuit package as in claim 1, wherein said pattern of contact pads forms a land grid array, and wherein said number of annular ring shaped alignment pads is three, said integrated circuit package further comprising:
 - 5 a) a wetting media deposited to said annular ring shaped alignment pads; and
 - b) an alignment ball attached to each of said annular ring shaped alignment pads via said wetting media, wherein said alignment balls are hard enough to resist deformation as said integrated circuit package is aligned with an interface.
- 10 12. An integrated circuit package as in claim 1, wherein said pattern of contact pads forms a land grid array, and wherein said number of annular ring shaped alignment pads is three, said integrated circuit package further comprising:
 - 5 a) a wetting media deposited to said annular ring shaped alignment pads; and
 - b) an alignment bullet attached to each of said annular ring

10 shaped alignment pads via said wetting media, wherein said alignment bullets are hard enough to resist deformation as said integrated circuit package is aligned with an interface, wherein each alignment bullet has an end with a raised disc which is shaped to protrude into one of the annular ring shaped alignment pads, and wherein at least one of said alignment bullets has a height which is greater than its diameter.

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13. An integrated circuit package, comprising:
 - a) a pattern of contact pads applied to a surface of the integrated circuit package; and
 - b) a number of alignment bullets attached to said surface at known locations with respect to said pattern of contact pads.
 14. An integrated circuit package as in claim 13, wherein at least one of said number of alignment bullets is hard enough to resist deformation as said integrated circuit package is aligned with an interface.
 15. An integrated circuit package as in claim 13, further comprising a number of alignment pads applied to said surface at known locations with respect to said pattern of contact pads, said number of alignment bullets being attached to said number of alignment pads.
 16. An integrated circuit package as in claim 15, wherein said number of alignment pads is three.
 17. An integrated circuit package as in claim 15, wherein said number of alignment members is attached to said number of alignment pads via said wetting media.

18. An integrated circuit package as in claim 13, wherein said pattern of contact pads forms a land grid array, wherein said number of alignment bullets is three, and wherein said alignment bullets are hard enough to resist deformation as said integrated circuit package is aligned with an interface, said integrated circuit package further comprising:
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- a) three alignment pads applied to said surface at known locations with respect to said pattern of contact pads; and
 - b) a wetting media deposited to said alignment pads, said alignment bullets being attached to said alignment pads via said wetting media.
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19. A method of providing an integrated circuit package with an alignment mechanism, comprising:
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- a) applying a pattern of contact pads to the integrated circuit package; and
 - b) applying a number of annular ring shaped alignment pads to said integrated circuit package, at known locations with respect to said pattern of contact pads.
20. A method as in claim 19, further comprising attaching a number of alignment members to said number of annular ring shaped alignment pads.
21. A method as in claim 20, further comprising:
- a) applying a wetting media to said number of annular ring shaped alignment pads; and
 - b) heating said wetting media; and
 - c) attaching said number of alignment members to said number of annular ring shaped alignment pads while said wetting media is
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heated.

22. A method as in claim 19, further comprising applying said pattern of contact pads and number of annular ring shaped alignment pads to the integrated circuit package at a same time.
23. A method of providing an integrated circuit package with an alignment mechanism, comprising:
- a) heating a wetting media which is applied to a number of annular ring shaped alignment pads provided on said integrated circuit package at known locations with respect to a pattern of contacts pads provided on said integrated circuit package; and
 - b) attaching a number of alignment members to said number of annular ring shaped alignment pads while said wetting media is heated.
24. A method as in claim 23, wherein one of said alignment members is an alignment bullet having an end which is shaped to protrude into one of said number of annular ring shaped alignment pads, and wherein the method further comprises placing said end of said alignment bullet in contact with one the wetting media which is applied to one of said alignment pads.
25. A method of providing an integrated circuit package with an alignment mechanism, comprising:
- a) heating a wetting media which is applied to a number of alignment pads provided on said integrated circuit package at known locations with respect to a pattern of contacts pads provided on said integrated circuit package; and

- b) attaching a number of alignment bullets to said number of alignment pads while said wetting media is heated.

26. An integrated circuit package, comprising:

- a) electrical contact means applied to a surface of the integrated circuit package; and
- b) a number of annular ring shaped alignment means applied to said surface at known locations with respect to said electrical contact means.

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27. An integrated circuit package, comprising:

- a) electrical contact means applied to a surface of the integrated circuit package; and
- b) bullet shaped alignment means attached to said surface at known locations with respect to said electrical contact means.

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